

Dual N-Channel 60 V (D-S) MOSFET

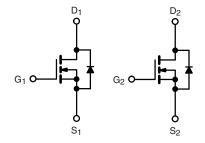
PRODUCT SUMMARY					
V _{DS} (V)	60				
$R_{DS(on)}(\Omega)$ at $V_{GS} = 10 \text{ V}$	0. 032				
$R_{DS(on)}(\Omega)$ at $V_{GS} = 4.5 \text{ V}$	0. 040				
I _D (A) per leg	6				
Configuration	Dual				

SO-8 Dual $\begin{array}{c} D_2 \\ D_2 \\ D_3 \\ D_4 \\ 7 \\ 8 \\ \end{array}$

FEATURES

- TrenchFET® power MOSFET
- \bullet 100 % R_g and UIS tested





N-Channel MOSFET N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS	(T _C = 25 °C, unles	s otherwise noted	d)	
PARAMETER	SYMBOL	LIMIT	UNIT	
Drain-Source Voltage		V_{DS}	60	V
Gate-Source Voltage	V_{GS}	± 20		
Continuous Drain Current	T _C = 25 °C	1	6	
Continuous Drain Current	T _C = 125 °C	- I _D	4	
Continuous Source Current (Diode Conduction) ^a		I _S	3.6	Α
Pulsed Drain Current ^b		I _{DM}	50	
Single Pulse Avalanche Current	L = 0.1 mH	I _{AS}	18	
Single Pulse Avalanche Energy	L = 0.1 IIII	E _{AS}	16	mJ
Maximum Power Dissipation ^b	T _C = 25 °C	Б	4	W
	T _C = 125 °C	P_{D}	1.3	VV
Operating Junction and Storage Temperature Range		T _J , T _{stg}	-55 to +175	°C

THERMAL RESISTANCE RATINGS						
PARAMETER		SYMBOL	LIMIT	UNIT		
Junction-to-Ambient	PCB Mount ^c	R_{thJA}	110	°C/W		
Junction-to-Foot (Drain)		R_{thJF}	34	C/VV		

Notes

- a. Package limited.
- b. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- c. When mounted on 1" square PCB (FR4 material).

1



PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static	•	•				•	
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		60	-	-	.,
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} =	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$			2.5	V
Gate-Source Leakage	I _{GSS}	V _{DS} =	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$		-	± 100	nA
		$V_{GS} = 0 V$	V _{DS} = 60 V	-	-	1	
Zero Gate Voltage Drain Current	I _{DSS}	$V_{GS} = 0 V$	$V_{DS} = 60 \text{ V}, T_{J} = 125 ^{\circ}\text{C}$	-	-	50	μΑ
		$V_{GS} = 0 V$	$V_{DS} = 60 \text{ V}, T_{J} = 175 ^{\circ}\text{C}$	-	-	150	
On-State Drain Current ^a	I _{D(on)}	$V_{GS} = 10 \text{ V}$	$V_{DS} \ge 5 V$	20	-	-	Α
		V _{GS} = 10 V	I _D = 4.5 A-			0.032	Ω
Drain-Source On-State Resistance a	R _{DS(on)}	$V_{GS} = 10 \text{ V}$	I _D = 4.5 A, T _J = 125 °C	-	-	0.060	
Drain Godree On Glate Nesistance	1 103(011)	$V_{GS} = 10 \text{ V}$	I _D = 4.5 A, T _J = 175 °C	-	-	0.081	
		$V_{GS} = 4.5 \text{ V}$	I _D = 4 A-			0.040	
Forward Transconductance f	9fs	V _{DS} = 15 V, I _D = 4.5 A		-	15	_	S
Dynamic ^b						1	1
Input Capacitance	C _{iss}			-	600	750	
Output Capacitance	C _{oss}	$V_{GS} = 0 V$	$V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$	-	110	140	pF
Reverse Transfer Capacitance	C _{rss}			-	50	62	
Total Gate Charge ^c	Qg			-	-	11.7	
Gate-Source Charge ^c	Q _{gs}	V _{GS} = 10 V	$V_{DS} = 30 \text{ V}, I_D = 5.3 \text{ A}$	-	-	1.8	nC
Gate-Drain Charge ^c	Q_{gd}			-	-	2.8	
Gate Resistance	R_g	f = 1 MHz		1.3	-	6	Ω
Turn-On Delay Time ^c	t _{d(on)}			-	7	11	
Rise Time ^c	t _r	$V_{DD} = 30 \text{ V, } R_L = 6.8 \Omega$ $I_D \cong 4.4 \text{ A, } V_{GEN} = 10 \text{ V, } R_g = 1 \Omega$		-	3.3	5	- ns
Turn-Off Delay Time ^c	t _{d(off)}			-	22.4	33.5	
Fall Time ^c	t _f			-	2.1	3.2	
Source-Drain Diode Ratings and Chara	acteristics b					1	
Pulsed Current ^a	I _{SM}				_	28	Α
Forward Voltage	V _{SD}	I _F = 2 A, V _{GS} = 0 V			0.75	1.1	V

Notes

- a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %. b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

25

20

15

10

5

0

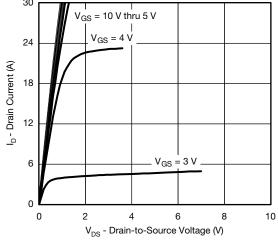
0

3

g fs - Transconductance (S)



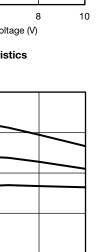
TYPICAL CHARACTERISTICS ($T_A = 25 \, ^{\circ}C$, unless otherwise noted)



Output Characteristics

 $T_C = -55$ °C

T_C = 25 °C



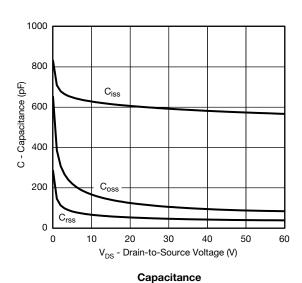
I_D - Drain Current (A) **Transconductance**

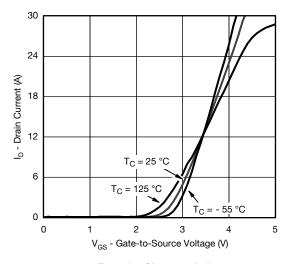
9

12

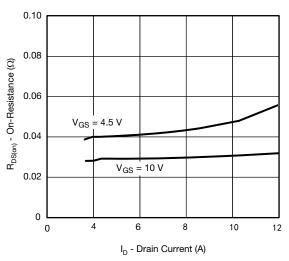
15

T_C = 125 °C

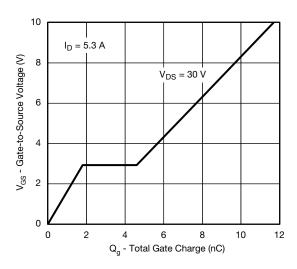




Transfer Characteristics



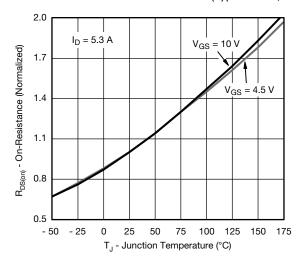
On-Resistance vs. Drain Current



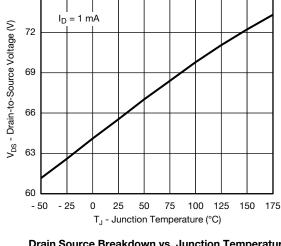
Gate Charge



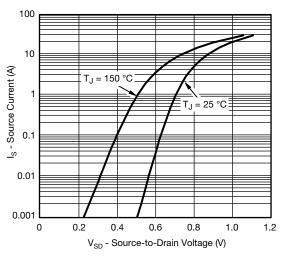
TYPICAL CHARACTERISTICS ($T_A = 25$ °C, unless otherwise noted)



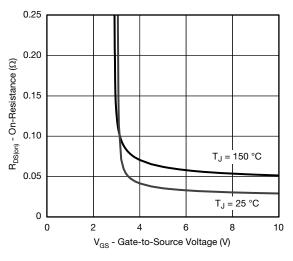
On-Resistance vs. Junction Temperature



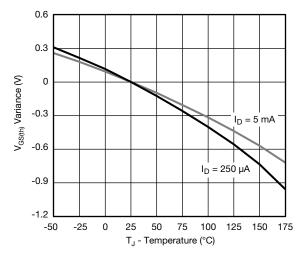
Drain Source Breakdown vs. Junction Temperature



Source Drain Diode Forward Voltage



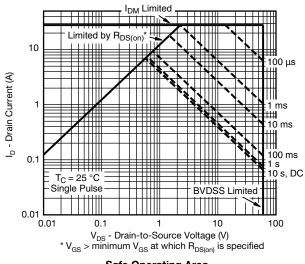
On-Resistance vs. Gate-to-Source Voltage



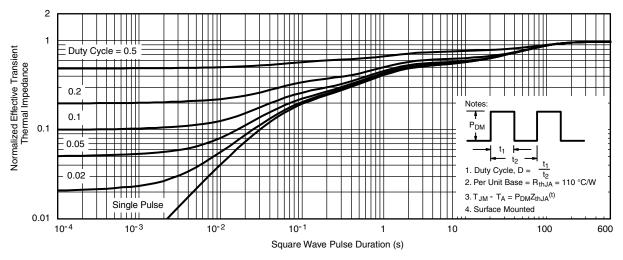
Threshold Voltage



THERMAL RATINGS ($T_A = 25$ °C, unless otherwise noted)



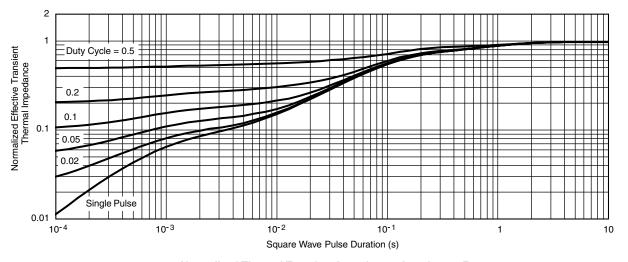
Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Ambient



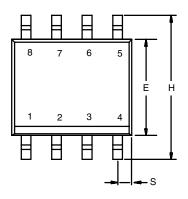
THERMAL RATINGS ($T_A = 25 \, ^{\circ}\text{C}$, unless otherwise noted)

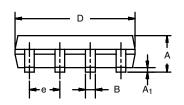


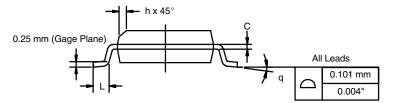
Normalized Thermal Transient Impedance, Junction-to-Foot



SOIC (NARROW): 8-LEAD JEDEC Part Number: MS-012





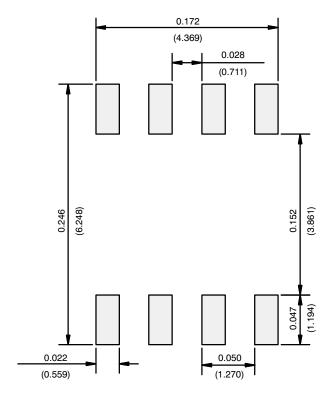


	MILLIMETERS		INC	HES		
DIM	Min	Max	Min	Max		
Α	1.35	1.75	0.053	0.069		
A ₁	0.10	0.20	0.004	0.008		
В	0.35	0.51	0.014	0.020		
С	0.19	0.25	0.0075	0.010		
D	4.80	5.00	0.189	0.196		
Е	3.80	4.00	0.150	0.157		
е	1.27	BSC	0.050 BSC			
Н	5.80	6.20	0.228	0.244		
h	0.25	0.50	0.010	0.020		
L	0.50	0.93	0.020	0.037		
q	0°	8°	0°	8°		
S	0.44	0.64	0.018	0.026		
ECN: C-06527-Rev. I. 11-Sep-06						

DWG: 5498



RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)

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